

2019 DESIGN FOR RELIABILITY CONFERENCE

AGENDA

Location: Hyatt Regency Baltimore Inner Harbor

Date: March 25 – 27, 2019



#TheFutureIsNow

Monday, March 25, 2019

Time	Title	Presenters
8:00-9:00 am	Registration/Breakfast	
9:00-9:30 am	Welcome	Dr. Craig Hillman, DfR Solutions
9:30-10:15 am	Case Study: How Continental Automotive is Integrating Sherlock into their Design Process	Tony Asghari, Continental Automotive
10:15-10:20 am	Break	
10:20-11:05 am	What's New with Sherlock?	Dr. Natalie Hernandez, DfR Solutions
11:05-11:50 pm	Will Your Battery Protection System and UL Test Prevent Catastrophic Lithium Ion Failures?	Dr. Vidyu Challa, DfR Solutions
11:50-1:00 pm	Lunch	
1:00-1:45 pm	DfX in Electronics Packaging	Kayleen Helms, Intel
1:45-1:50 pm	Break	
1:50-2:35 pm	Warranty-Reliability-Maintainability: How Optimal+/Sherlock Allow for Comprehensive Prediction Throughout the Product Lifecycle	Dan Sebban, Optimal Plus
2:35-2:40 pm	Break	
2:40-3:25 pm	Case Study: Solder Fatigue Model Verification using NAND BGAs	Ken Symonds, Western Digital
3:25-3:30 pm	Break	
3:30-4:15 pm	Best Practices in Reliability Management of Consumer Electronics	Ed Tinsley, Dell
4:15-5:00 pm	Electrical Overstress (EOS) in Semiconductors: An Introduction to Electrically Induced Physical Damage	Ashok Alagappan, DfR Solutions & Stevan Hunter, Onsemi
5:00-7:00 pm	Welcome Reception	

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Tuesday, March 26, 2019

Time	Title	Presenters
8:00-9:00 am	Breakfast	
9:00-9:45 am	How to Implement a Proactive Approach to Identifying Reliability Risks	John Coates, ZF
9:45-9:50 am	Break	
9:50-10:35 am	Using Simulation to Optimize Microvia Placement and Materials to Avoid Failures During Reflow	Dr. Nathan Blattau, DfR Solutions
10:35-10:40 am	Break	
10:40-11:25 pm	A Corporate-Level Process Flow to Ensure Quality and Reliability	Marty Novak, Arris
11:25-12:10 pm	Using RPA to Predict Thermal Cycling BGA Failures for Aircraft Engines	Don McNally, Woodward
12:10-1:05 pm	Lunch	
1:05-1:50 pm	How to Use Sherlock to Perform a Pre-HALT	Joe Powell, Lennox
1:50-2:00 pm	Break	
2:00-2:45 pm	Accurately Capturing System-Level Failures of Solder Joints	Maxim Serebreni, DfR Solutions
2:45-2:50 pm	Break	
2:50-3:35 pm	Reliable Sensors Engineering: Key Enabler for Commercial Autonomous Vehicles	Puneet Sinha, Mentor
3:35-3:40 pm	Break	
3:40-4:25 pm	How to Successfully Implement J3168 SAE Standards in Your Supply Chain	Jim McLeish & Lloyd Condra, DfR Solutions
4:25-5:10 pm	Understanding and Mitigating Chip-Package-Board Interaction (CPBI)	Dr. Gil Sharon, DfR Solutions

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Wednesday, March 27, 2019

Track 1

Sherlock Automated Design Analysis™ Software Technical Training

Time	Title	Presenter
8:00-9:00 am	Breakfast	
9:00 – 10:00 am	Define Lifecycle, Picking Critical Components, Board Outline Without Layout, Full Layout, Vibration & Shock	Multiple Technical staff
10:00 – 10:15am	Break	
10:15-11:45 am	Starting a Sherlock project: Defining Lifecycles, Critical Components, and Mechanical Loading.	Multiple Technical staff
11:45-12:45 pm	Lunch	
12:45-1:45 pm	Solving Thermal Mechanical and ICT problems, one Sherlock project at a time	Multiple Technical staff
1:45-2:45 pm	Live Demo: Your Sherlock projects, reviewed live!	Multiple Technical staff
2:45–3:00 pm	Break	
3:00–4:30 pm	Q&A Ask Us Anything	Multiple Technical staff

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Wednesday, March 27, 2019

Track 2

How to Qualify Your Batteries to Prevent Failures & Thermal Events

Time	Title	Presenter
8:00-9:00 am	Breakfast	
9:00-12:00 am	Battery Workshop	Dr. Vidyu Challa, DfR Solutions

The rising demand for Internet of things (IoT) and machine-to-machine (M2M) applications makes battery power an absolute necessity. However, reports about lithium-ion batteries exploding and catching fire continue to draw the public's attention. How do you balance the need for power, size, cost, and time-to-market, while still avoiding being the lead story on the evening news?

Is it enough to qualify a cell manufacturer according to industry standards? The answer is that the majority of compliance-based testing is related to abuse tolerance. However, the vast majority of field failures do not occur under abuse scenarios, but happen under normal operating conditions due to manufacturing flaws or design and system tolerance issues that cause internal shorts. Internal shorts are unfortunately not mitigated by safety electronics.

In this battery workshop, you:

- Gain an understanding of lithium-ion battery failure mechanisms and the pathway to thermal runaway events
- Learn about the top causes of battery field failures, and the major areas where you need to have mitigation strategies
- Learn how cell design plays a critical role in battery safety and reliability, and what you can do from a design perspective to prevent these failures
- Learn the basic steps in a lithium-ion cell manufacturing process, and the process controls required to ensure cell safety and reliability
- Learn about the battery management system and its role in system safety
- Come away with a checklist of things you should do to qualify your cell manufacturer – pass down requirements, trust but verify (design, manufacturing, compliance-based testing, system-level tolerances, application-specific battery testing, battery management system, cell CT scans and teardowns and lastly user education)

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Poster Sessions

Title	Presenters
Risks of Wide Band Gap (WBG) Semiconductors in Power Supply Applications	Craig Hillman, DfR Solutions
Predicting the Failure Rate of Next Generation Integrated Circuits using Reliability Physics	Ashok Allagappan, DfR Solutions
Extending Product Life of Electronic Systems through Reliability Centered Maintenance (RCM)	Ed Dodd, DfR Solutions
Practical application of AEC requirements for automotive components (passives and ICs)	Chris South, DfR Solutions
Key Lessons from Performing Finite Element Analysis (FEA) on Semiconductor Packaging, Printed Circuit Boards, and Electronic Assemblies	Josh Akman & Tyler Ferris, DfR Solutions
Accelerated Radiation Susceptibility Analysis and Prediction (RadSAP) Tool	Greg Caswell & Ashok Allagappan, DfR Solutions
Design for Reliability for Connectors: A Review of Failure Modes and Mitigations	Michael Blattau, DfR Solutions